



Printed Circuit Boards
Interconnection Carriers

State of the Art: PCB's

Revisio

Datum:

Seite:

PRINTED CIRCUIT BOARDS

01

4.11.2001

1/1

Schematic Key for Multilayer and HDI-Technology Build-Ups

| a | b | c | d | e | f | g + h + i |
|---|---|---|---|---|---|-----------|
|---|---|---|---|---|---|-----------|

04 159 FR4 60 L41.70 P18_10

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

04_159_FR4_60_L41.70_p18_10

| Layers | in μ | Material | Build-Up | Assembly | |
|----------|-----------|----------|----------|----------|--------------------------------|
| Layer-1 | 60 μ | Copper | | | |
| | 100 μ | Prepreg | | | (100 μ PrePreg-Type: 2125) |
| | 180 μ | Prepreg | | | (180 μ PrePreg-Type: 7628) |
| | 180 μ | Prepreg | | | |
| Layer-2 | 70 μ | Copper | | | |
| | 410 μ | L-FR4 | | | |
| Layer-3 | 70 μ | Copper | | | |
| | 180 μ | Prepreg | | | |
| | 180 μ | Prepreg | | | |
| | 100 μ | Prepreg | | | |
| Layer-99 | 60 μ | Copper | | | |

© Copyright by Printed Circuit Boards GmbH